

1. 封裝 Package

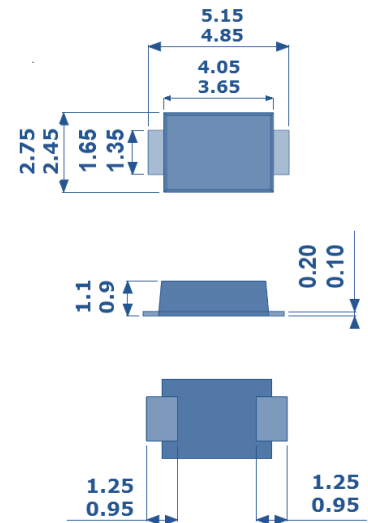
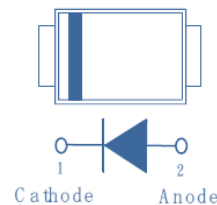
- 封裝方式 Method: SMAF
- 封裝尺寸 Dimension: 如圖示

2. 產品特色 Features

- For surface mounted applications in order to optimize board space
- High temperature metallurgically bonded-no compression
- Easy pick and place
- Glass passivated junction
- Meet with EU RoHS 2011/65/EU compliance
- Lead free and Green device

3. 機械數據 Mechanical Data

- Epoxy: UL94V-0 rated flame retardant
- Case: Epoxy, Molded
- Terminals: Solder plated solderable per MIL-STD-750 Method 2026
- Polarity: Color band denotes cathode end



單位 Unit: millimeters

4. 極限值與電參數 Maximum Ratings & Electrical Characteristic

Rating at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz, resistive or inductive load. For capacitive load, derate current by 20%.

	Symbol	ES2AAF	ES2BAF	ES2DAF	ES2GAF	ES2JAF	UNITS
Marking Code	-	ES2AA	ES2BA	ES2DA	ES2GA	ES2JA	-
Recurrent Peak Reverse Voltage	V _{RRM}	50	100	200	400	600	Volts
RMS Voltage	V _{RMS}	35	70	105	280	420	Volts
DC Blocking Voltage	V _R	50	100	200	400	600	Volts
Peak Forward Surge Current: 8.3ms single half sine -wave superimposed on rated load	I _{FSM}	50					Amps
Average Forward Current	I _{F(AV)}	2.0					Amps
Forward Voltage at 2.0A	V _F	0.95			1.25	1.7	Volts
DC Reverse Current at Rated DC Blocking Voltage T _J =25°C	I _R	1					mA
Operating Junction Temperature and Storage Temperature	T _J ,T _{STG}	-55~+150					°C
Typical thermal resistance, Junction to Lead(Note1)	R _{θJL}	18					°C/W
Junction to Ambient(Note2)	R _{θJA}	135					
Reverse Recovery Time (I _F =0.5A, I _R =1A, I _{rr} =0.25A)	T _{rr}	35					nS

Notes:

- (1) Mounted on an FR4 PCB, single-sided copper, with 48cm²copper pad area.
- (2) Mounted on an FR4 PCB, single-sided copper, mini pad.

5. 特性曲線 Rating & Characteristic Curves

Fig. 1 Forward Current Derating Curve

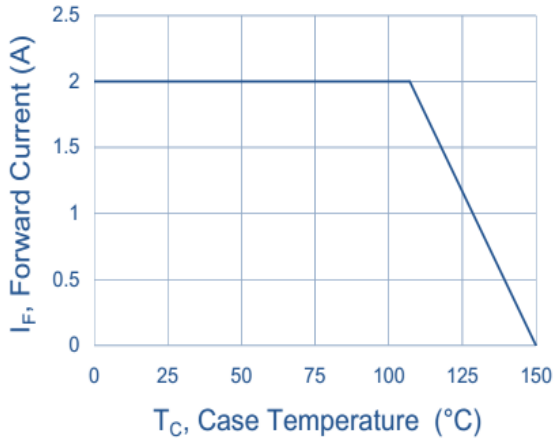


Fig. 2 Typical Reverse Characteristics

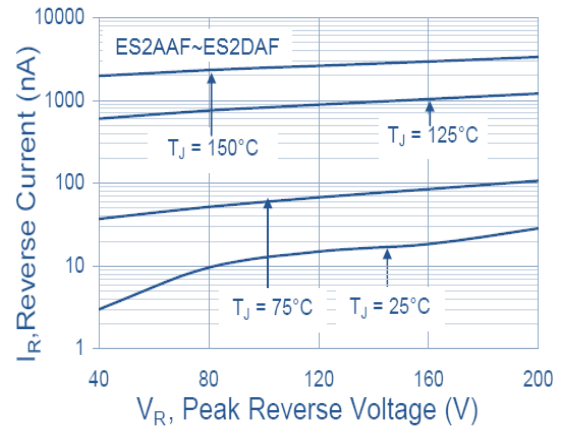


Fig. 3 Typical Reverse Characteristics

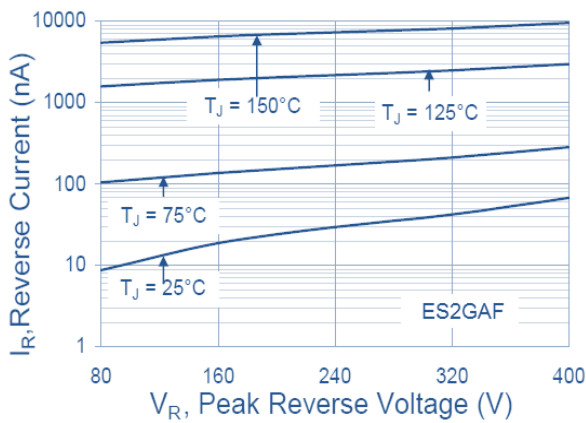


Fig. 4 Typical Reverse Characteristics

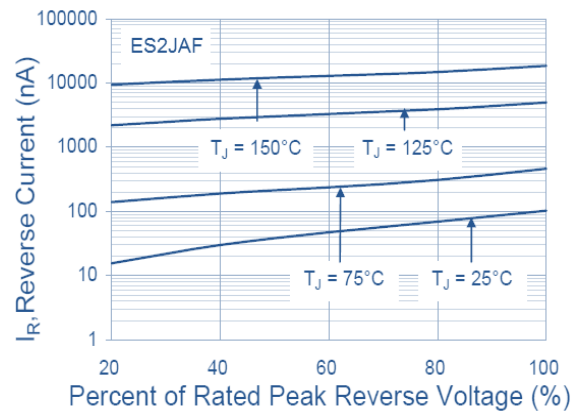


Fig. 5 Typical Forward Characteristics

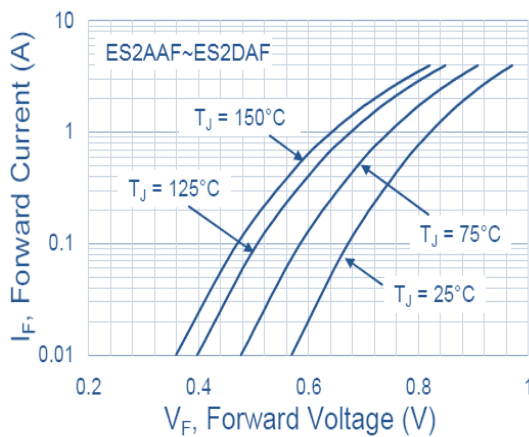


Fig. 6 Typical Forward Characteristics

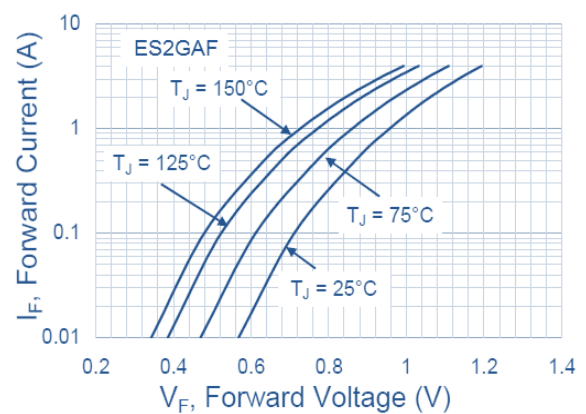
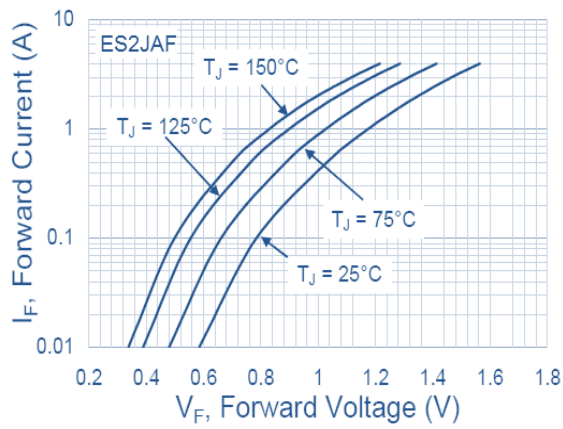
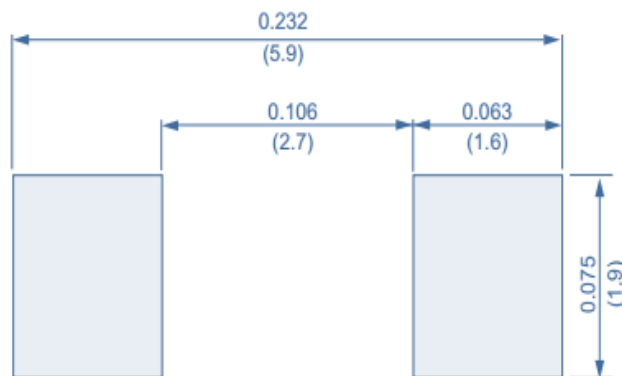


Fig. 7 Typical Forward Characteristics



Pad Layout



Unit: inch (mm)